



Flexible Devices for Medical Applications

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Message from the Guest Editors

Dear Colleagues,

Flexible devices have been developed as medical tools with a high conformability, due to their micrometer scale thickness, over the past few years. With the recent improvements in flexible device technology, various medical applications have been introduced, including bio-electrical signal sensors, bio-chemical signal sensors, electroceutical treatment, and drug-delivery systems. With this sensing and treatment technology, flexible biomedical devices have enabled a wide range of clinical applications, such as for epilepsy, heart failure monitoring systems, wound healing, and metabolic disease monitoring systems and treatment. Accordingly, this Special Issue seeks to showcase research papers and review articles that focus on novel microfabrication in flexible devices, and its use for various biomedical applications.

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